

IN THE CLAIMS

Claim 1 (previously presented) A separator plate for the production of printed circuit board components by pressing individual layers, which separator plate comprises a metallic core layer and a metal layer on at least one side of the core layer, wherein the core layer comprises a comparatively high heat-conductive metal, the core layer having an outer surface on which said metal layer is applied by cold plating, said metal layer being made of a metal having a comparatively high surface hardness compared to the core layer and a lower heat conductivity than said core layer, said separator plate being interposed between stacks of printed circuit board layers which are subjected to compression under heat, said separator plate being a composite of said core layer and said outer metal layer to provide reduced heat expansion of the core layer during pressing of the individual layers of the circuit board components while preventing image transfer to the separator plate.

Claim 2 (previously presented) A separator plate according to claim 1, wherein the core layer comprises on either side a said outer metal layer applied by cold-plating having the comparatively high surface hardness.

Claim 3 (previously presented) A separator plate according to claim 1, wherein the outer metal layer is applied to the core layer by roll-bonding.

Claim 4 (previously presented) A separator plate according to claim 1, wherein the outer metal layer is made of steel.

Claim 5 (original) A separator plate according to claim 1, wherein the outer metal layer is made of nickel.

Claim 6 (original) A separator plate according to claim 1, wherein the core layer is made of aluminum.

Claim 7 (original) A separator plate according to claim 1, wherein the core layer is made of copper.

Claim 8 (original) A separator plate according to claim 1, wherein the core layer has a thickness of about 0.35 mm.

Claim 9 (original) A separator plate according to claim 1, wherein the outer metal layer has a thickness of about 0.075 mm.

Claim 10 (original) A separator plate according to claim 1, wherein a lubricant is applied to the outer metal layer.

Claim 11 (previously presented) A separator plate according to claim 10, wherein the lubricant is based on an olefin.

Claim 12 (previously presented) A separator plate according to claim 2, wherein the outer metal layer is applied to the core layer by roll-bonding.

Claim 13 (cancelled)

Claim 14 (cancelled)

Claim 15 (previously presented) A separator plate for the production of printed circuit board components by pressing individual layers, which separator plate comprises a metallic core layer and a metal layer on at least one side of the core layer, wherein the core layer comprises a comparatively high heat-conductive metal, the core layer having an outer surface on which said metal layer is applied by cold plating, said metal layer being made of a metal having a comparatively high surface hardness compared to the core layer and a lower heat conductivity than said core layer, said separator plate being interposed between stacks of printed circuit board layers which are subjected to compression under heat, said separator plate being a composite of said core layer and said outer metal layer to provide reduced heat expansion of the core layer during pressing of the individual layers of the circuit board

components while preventing image transfer to the separator plate, said core layer having a thickness of about 0.35 mm, said outer metal layer having a thickness of about 0.075 mm, said outer metal layer having a smooth outer surface for intimate contact with the adjacent individual layers, said high surface hardness of the outer metal layer serving as a means for resisting pressure in the press and preventing disruption of the individual layers and image transfer to the separator plate, said core layer of high heat conductivity then serving as a means for providing uniform heat distribution to the adjacent individual layers.